### 503523570 10/14/2015

### PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

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EPAS ID: PAT3570196

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Chih-Wen Huang	08/28/2015
Yu-Chiao Chen	08/28/2015

#### **RECEIVING PARTY DATA**

Name:	WIN Semiconductors Corp.
Street Address:	69, Technology 7th Rd., Hwaya Technology Park, Kuei Shan Dist.
City:	Tao Yuan City
State/Country:	TAIWAN

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14883609

#### **CORRESPONDENCE DATA**

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using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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**Correspondent Name:** WINSTON HSU **Address Line 1:** P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	WFDP0005USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	10/14/2015

#### **Total Attachments: 4**

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PATENT 503523570 REEL: 036795 FRAME: 0473

## COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of	Invention	:
High-Fi	requency	Package

As the below named inventor, I hereby declare the This declaration is directed to:	at:	
☑ The attached application, or		
☐ United States application number	filed on, or	
□ PCT international application number	filed on	_
The above-identified application was made or auti	horized to be made by me.	
I believe that I am the original inventor or an original application.	nal joint inventor of a claimed invention in the	
I hereby acknowledge that any willful false statem under18 U.S.C. 1001 by fine or imprisonment of n		
In consideration of the payment by WIN Semic	conductors Corp. having a postal address	s of
69, Technology 7th Rd., Hwaya Technolo Taiwan, R.O.C.	ogy Park, Kuei Shan Dist., Tao Yuan City 3	33,
(referred to as "ASSIGNEE"below) to I of the sum acknowledged, andfor other good and valuable co	of One Dollar (\$ 1.00), the receipt of which is hereby onsideration.	/
I hereby sell, assign and transfer to ASSIGNEE are the entire right, title and interest in and to any and invention as above-identified application and, in all invention by the above application or any continual substitutes, or extensions thereof, and as to Letter	nd to, all Letters Patent to be obtained for said stions, continuation-in-part, divisions, renewals,	
I hereby covenant that no assignment, sale, agree entered into which would conflict with this assignment.	ement or encumbrance has been or will be made or nent;	
I further covenant that ASSIGNEE will, upon its re and documents relating to said invention and said known and accessible to I and will testify as to the related thereto and will promptly execute and deliv	same in any interference, litigation proceeding	
representatives any and all papers, instruments or maintain, issue and enforce said application, said equivalents thereof which may be necessary or de IN WINTNESS WHEREOF, I have hereunto set ha	invention and said Letters Patent and said sairable to carry out the proposes thereof.	jning)
Note: An application data sheet (PTO/SB/14 or eq inventive entity, must accompany this form. Use the	uivalent), including naming the entire	

NPO#WFD-P0005-USA:0 CUST# Page 1 of 4

F#NPO-P0002E-US1201 DSB0-104U024916

PATENT REEL: 036795 FRAME: 0474

Docket No. WFDP0005USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Chih-Wen Huang Inventor:

Date:

NPO#WFD-P0005-USA:0 CUST#

F#NPO-P0002E-US1201 DSB0-104U024916

**PATENT REEL: 036795 FRAME: 0475** 

2015/08/28 10:03 yltseng

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention: High-Frequency Package

	1965 1967 - States	
As the below named inventor, I hereby declare that: This declaration is directed to:		
☑ The attached application, or	19	
□United States application number	filed on	, or
□PCT international application number	filed on	***************************************
The above-identified application was made or authorized to be	e made by me.	
I believe that I am the original inventor or an original joint inventor application.	ntor of a claimed invention in th	ne Rojenski
I hereby acknowledge that any willful false statement made in under18 U.S.C. 1001 by fine or imprisonment of not more than	this declaration is punishable in five (5) years, or both	
In consideration of the payment by WIN Semiconductor	s Corp. having a posta	al address of
69, Technology 7th Rd., Hwaya Technology Park, I Taiwan, R.O.C.	Kuei Shan Dist., Tao Yua	n City 333,
(referred to as "ASSIGNEE"below) to I of the sum of One Dolla acknowledged, andfor other good and valuable consideration.	ar (\$ 1.00), the receipt of which	is hereby
I hereby sell, assign and transfer to ASSIGNEE and the succe the entire right, title and interest in and to any and all improver invention as above-identified application and, in and to, all Lett invention by the above application or any continuations, continuations, continuations, or extensions thereof, and as to Letters Patent any	nents which are disclosed in th ters Patent to be obtained for s uation-in-part, divisions, renew	e aid als
I hereby covenant that no assignment, sale, agreement or encentered into which would conflict with this assignment;	umbrance has been or will be r	made or
I further covenant that ASSIGNEE will, upon its request, be pro and documents relating to said invention and said Letters Pate known and accessible to   and will testify as to the same in any related thereto and will promptly execute and deliver to ASSIG	ent and legal equivalents as ma vinterference, litigation proceed	iv be
representatives any and all papers, instruments or affidavits re maintain, issue and enforce said application, said invention an equivalents thereof which may be necessary or desirable to ca IN WINTNESS WHEREOF, I have hereunto set hand and seal	d said Letters Patent and said rry out the proposes thereof.	Pate of signing)
Note: As a self-cities data about (DTO/OD/44		
Note: An application data sheet (PTO/SB/14 or equivalent), inc inventive entity, must accompany this form. Use this form for <u>e</u>	uging naming the entire ach additional inventor.	
	86, 186,	

NPO#WFD-P0005-USA:0 CUST# Page 3 of 4

F#NPO-P0002E-US1201 DSB0-104U024916

PATENT REEL: 036795 FRAME: 0476

Docket No WFDP0005USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Yu-Chiao Chen

Date:

>015/8/28

Signature:

NPO#WFD-P0005-USA:0 CUST# Page 4 of

F#NPO-P0002E-US1201 DSB0-104U024916

PATENT REEL: 036795 FRAME: 0477

<sup>2015/08/</sup>RECORDED: 10/14/2015